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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

#### **Details**

Product Status	Active
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	336
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/ax500-fgg676">https://www.e-xfl.com/product-detail/microchip-technology/ax500-fgg676</a>

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of  $\theta_{JC}$ .

**Table 2-6 • Package Thermal Characteristics**

Package Type	Pin Count	$\theta_{JC}$	$\theta_{JA}$ Still Air	$\theta_{JA}$ 1.0m/s	$\theta_{JA}$ 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP) <sup>1</sup>	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP) <sup>1</sup>	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA) <sup>2</sup>	624	6.5	8.9	8.5	8	°C/W

Notes:

1.  $\theta_{JC}$  for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.
2.  $\theta_{JC}$  for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board ( $\theta_{JB}$ ) for CCGA 624 package is 3.4°C/W.

## Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

**Table 2-7 • Temperature and Voltage Timing Derating Factors**  
(Normalized to Worst-Case Commercial,  $T_J = 70^\circ\text{C}$ ,  $VCCA = 1.425\text{V}$ )

VCCA	Junction Temperature						
	-55°C	-40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. The user can set the junction temperature in Designer software to be any integer value in the range of -55°C to 175°C.
2. The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

Table 2-15, Table 2-16, and Table 2-17 list all the available macro names differentiated by I/O standard, type, slew rate, and drive strength.

**Table 2-15 • Macros for Single-Ended I/O Standards**

Standard	VCCI	Macro Names
LVTTL	3.3 V	CLKBUF, HCLKBUF_INBUF, OUTBUF, OUTBUF_S_8, OUTBUF_S_12, OUTBUF_S_16, OUTBUF_S_24, OUTBUF_H_8, OUTBUF_H_12, OUTBUF_H_16, OUTBUF_H_24, TRIBUF, TRIBUF_S_8, TRIBUF_S_12, TRIBUF_S_16, TRIBUF_S_24, TRIBUF_H_8, TRIBUF_H_12, TRIBUF_H_16, TRIBUF_H_24, BIBUF, BIBUF_S_8, BIBUF_S_12, BIBUF_S_16, BIBUF_S_24, BIBUF_H_8, BIBUF_H_12, BIBUF_H_16, BIBUF_H_24
3.3 V PCI	3.3 V	CLKBUF_PCI, HCLKBUF_PCI, INBUF_PCI, OUTBUF_PCI, TRIBUF_PCI, BIBUF_PCI
3.3 V PCI-X	3.3 V	CLKBUF_PCI-X, HCLKBUF_PCI-X, INBUF_PCI-X, OUTBUF_PCI-X, TRIBUF_PCI-X, BIBUF_PCI-X
LVCMOS25	2.5 V	CLKBUF_LVCMOS25, HCLKBUF_LVCMOS25, INBUF_LVCMOS25, OUTBUF_LVCMOS25, TRIBUF_LVCMOS25, BIBUF_LVCMOS25
LVCMOS18	1.8 V	CLKBUF_LVCMOS18, HCLKBUF_LVCMOS18, INBUF_LVCMOS18, OUTBUF_LVCMOS18, TRIBUF_LVCMOS18, BIBUF_LVCMOS18
LVCMOS15 (JESD8-11)	1.5 V	CLKBUF_LVCMOS15, HCLKBUF_LVCMOS15, INBUF_LVCMOS15, OUTBUF_LVCMOS15, TRIBUF_LVCMOS15, BIBUF_LVCMOS15

**Table 2-16 • I/O Macros for Differential I/O Standards**

Standard	VCCI	Macro Names
LVPECL	3.3 V	CLKBUF_LVPECL, HCLKBUF_LVPECL, INBUF_LVPECL, OUTBUF_LVPECL
LVDS	2.5 V	CLKBUF_LVDS, HCLKBUF_LVDS, INBUF_LVDS, OUTBUF_LVDS

**Table 2-17 • I/O Macros for Voltage-Referenced I/O Standards**

Standard	VCCI	VREF	Macro Names
GTL+	3.3 V	1.0 V	CLKBUF_GTP33, HCLKBUF_GTP33, INBUF_GTP33, OUTBUF_GTP33, TRIBUF_GTP33, BIBUF_GTP33
GTL+	2.5 V	1.0 V	CLKBUF_GTP25, HCLKBUF_GTP25, INBUF_GTP25, OUTBUF_GTP25, TRIBUF_GTP25, BIBUF_GTP25
SSTL2 Class I	2.5 V	1.25 V	CLKBUF_SSTL2_I, HCLKBUF_SSTL2_I, INBUF_SSTL2_I, OUTBUF_SSTL2_I, TRIBUF_SSTL2_I, BIBUF_SSTL2_I
SSTL2 Class II	2.5 V	1.25 V	CLKBUF_SSTL2_II, HCLKBUF_SSTL2_II, INBUF_SSTL2_II, OUTBUF_SSTL2_II, TRIBUF_SSTL2_II, BIBUF_SSTL2_II
SSTL3 Class I	3.3 V	1.5 V	CLKBUF_SSTL3_I, HCLKBUF_SSTL3_I, INBUF_SSTL3_I, OUTBUF_SSTL3_I, TRIBUF_SSTL3_I, BIBUF_SSTL3_I
SSTL3 Class II	3.3 V	1.5 V	CLKBUF_SSTL3_II, HCLKBUF_SSTL3_II, INBUF_SSTL3_II, OUTBUF_SSTL3_II, TRIBUF_SSTL3_II, BIBUF_SSTL3_II
HSTL Class I	1.5 V	0.75 V	CLKBUF_HSTL_I, HCLKBUF_HSTL_I, INBUF_HSTL_I, OUTBUF_HSTL_I, TRIBUF_HSTL_I, BIBUF_HSTL_I

**Table 2-22 • 3.3 V LVTTL I/O Module**Worst-Case Commercial Conditions  $VCCA = 1.425\text{ V}$ ,  $VCCI = 3.0\text{ V}$ ,  $T_J = 70^\circ\text{C}$  (continued)

Parameter	Description	-2 Speed		-1 Speed		Std Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>LVTTL Output Drive Strength = 2 (12 mA) / Low Slew Rate</b>								
$t_{DP}$	Input Buffer		1.68		1.92		2.26	ns
$t_{PY}$	Output Buffer		12.14		13.83		16.26	ns
$t_{ENZL}$	Enable to Pad Delay through the Output Buffer—Z to Low		12.43		14.16		16.65	ns
$t_{ENZH}$	Enable to Pad Delay through the Output Buffer—Z to High		12.17		13.86		16.30	ns
$t_{ENLZ}$	Enable to Pad Delay through the Output Buffer—Low to Z		1.73		1.74		1.75	ns
$t_{ENHZ}$	Enable to Pad Delay through the Output Buffer—High to Z		2.22		2.23		2.24	ns
$t_{IOLKQ}$	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
$t_{IOLKY}$	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
$t_{SUD}$	Data Input Set-Up		0.23		0.27		0.31	ns
$t_{SUE}$	Enable Input Set-Up		0.26		0.30		0.35	ns
$t_{HD}$	Data Input Hold		0.00		0.00		0.00	ns
$t_{HE}$	Enable Input Hold		0.00		0.00		0.00	ns
$t_{CPWHL}$	Clock Pulse Width High to Low		0.39		0.39		0.38	ns
$t_{CPWLH}$	Clock Pulse Width Low to High		0.39		0.39		0.39	ns
$t_{WASYN}$	Asynchronous Pulse Width		0.37		0.37		0.37	ns
$t_{REASYN}$	Asynchronous Recovery Time		0.13		0.15		0.17	ns
$t_{HASYN}$	Asynchronous Removal Time		0.00		0.00		0.00	ns
$t_{CLR}$	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
$t_{PRESET}$	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

## Timing Characteristics

**Table 2-25 • 2.5V LVC MOS I/O Module**

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, TJ = 70°C

Parameter	Description	-2 Speed		-1 Speed		Std Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>LVC MOS25 I/O Module Timing</b>								
t <sub>DP</sub>	Input Buffer		1.95		2.22		2.61	ns
t <sub>PY</sub>	Output Buffer		3.29		3.74		4.40	ns
t <sub>ENZL</sub>	Enable to Pad Delay through the Output Buffer—Z to Low		2.48		2.50		2.51	ns
t <sub>ENZH</sub>	Enable to Pad Delay through the Output Buffer—Z to High		2.48		2.50		2.51	ns
t <sub>ENLZ</sub>	Enable to Pad Delay through the Output Buffer—Low to Z		5.74		6.54		7.69	ns
t <sub>ENHZ</sub>	Enable to Pad Delay through the Output Buffer—High to Z		6.60		7.51		8.83	ns
t <sub>IOLCLKQ</sub>	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t <sub>IOLCLKY</sub>	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t <sub>SUD</sub>	Data Input Set-Up		0.23		0.27		0.31	ns
t <sub>SUE</sub>	Enable Input Set-Up		0.26		0.30		0.35	ns
t <sub>HD</sub>	Data Input Hold		0.00		0.00		0.00	ns
t <sub>HE</sub>	Enable Input Hold		0.00		0.00		0.00	ns
t <sub>CPWHL</sub>	Clock Pulse Width High to Low		0.39		0.39		0.39	ns
t <sub>CPWLH</sub>	Clock Pulse Width Low to High		0.39		0.39		0.39	ns
t <sub>WASYN</sub>	Asynchronous Pulse Width		0.37		0.37		0.37	ns
t <sub>REASYN</sub>	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t <sub>HASYN</sub>	Asynchronous Removal Time		0.00		0.00		0.00	ns
t <sub>CLR</sub>	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t <sub>PRESET</sub>	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

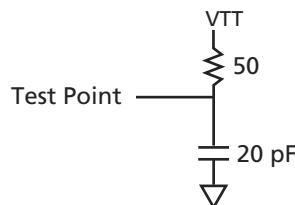
## HSTL Class I

High-Speed Transceiver Logic is a general-purpose high-speed 1.5 V bus standard (EIA/JESD8-6). The Axcelerator devices support Class I. This requires a differential amplifier input buffer and a push-pull output buffer.

**Table 2-41 • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	VREF - 0.1	VREF + 0.1	3.6	0.4	VCC - 0.4	8	-8

### AC Loadings



**Figure 2-20 • AC Test Loads**

**Table 2-42 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C <sub>load</sub> (pF)
VREF - 0.5	VREF + 0.5	VREF	0.75	20

Note: \* Measuring Point = VTRIP

### Timing Characteristics

**Table 2-43 • 1.5 V HSTL Class I I/O Module**

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.425 V, T<sub>J</sub> = 70°C

Parameter	Description	-2 Speed		-1 Speed		Std Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>1.5 V HSTL Class I I/O Module Timing</b>								
t <sub>DP</sub>	Input Buffer		1.80		2.05		2.41	ns
t <sub>PY</sub>	Output Buffer		4.90		5.58		6.56	ns
t <sub>ICLKQ</sub>	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t <sub>OCLKQ</sub>	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t <sub>SUD</sub>	Data Input Set-Up		0.23		0.27		0.31	ns
t <sub>SUE</sub>	Enable Input Set-Up		0.26		0.30		0.35	ns
t <sub>HD</sub>	Data Input Hold		0.00		0.00		0.00	ns
t <sub>HE</sub>	Enable Input Hold		0.00		0.00		0.00	ns
t <sub>CPWHL</sub>	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t <sub>CPWLH</sub>	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t <sub>WASYN</sub>	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t <sub>REASYN</sub>	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t <sub>HASYN</sub>	Asynchronous Removal Time		0.00		0.00		0.00	ns
t <sub>CLR</sub>	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t <sub>PRESET</sub>	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

## SSTL2

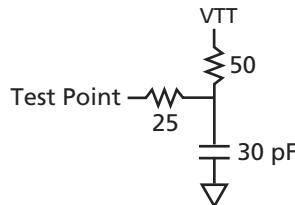
Stub Series Terminated Logic for 2.5 V is a general-purpose 2.5 V memory bus standard (JESD8-9). The Axcelerator devices support both classes of this standard. This requires a differential amplifier input buffer and a push-pull output buffer.

### Class I

**Table 2-44 • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	VREF - 0.2	VREF + 0.2	3.6	VREF - 0.57	VREF + 0.57	7.6	-7.6

### AC Loadings



**Figure 2-21 • AC Test Loads**

**Table 2-45 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C <sub>load</sub> (pF)
VREF - 0.75	VREF + 0.75	VREF	1.25	30

Note: \* Measuring Point = V<sub>TRIP</sub>

### Timing Characteristics

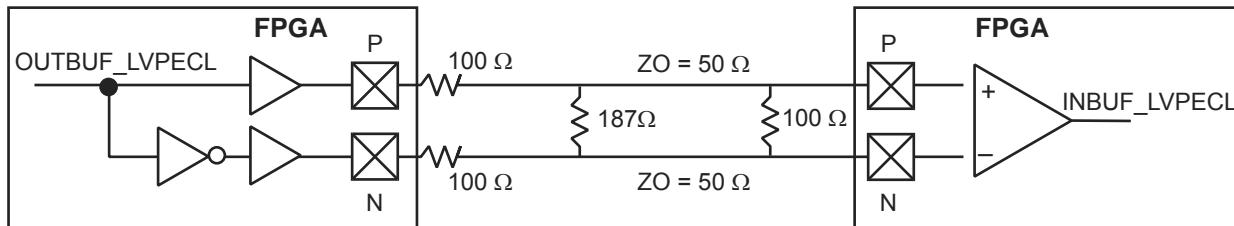
**Table 2-46 • 2.5 V SSTL2 Class I I/O Module**

Worst-Case Commercial Conditions V<sub>CCA</sub> = 1.425 V, V<sub>CCI</sub> = 2.3 V, T<sub>J</sub> = 70°C

Parameter	Description	-2 Speed		-1 Speed		Std Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>2.5 V SSTL2 Class I I/O Module Timing</b>								
t <sub>DP</sub>	Input Buffer		1.83		2.08		2.45	ns
t <sub>PY</sub>	Output Buffer		2.39		2.72		3.20	ns
t <sub>ICLKQ</sub>	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t <sub>OCLKQ</sub>	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t <sub>SUD</sub>	Data Input Set-Up		0.23		0.27		0.31	ns
t <sub>SUE</sub>	Enable Input Set-Up		0.26		0.30		0.35	ns
t <sub>HD</sub>	Data Input Hold		0.00		0.00		0.00	ns
t <sub>HE</sub>	Enable Input Hold		0.00		0.00		0.00	ns
t <sub>CPWHL</sub>	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t <sub>CPWLH</sub>	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t <sub>WASYN</sub>	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t <sub>REASYN</sub>	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t <sub>HASYN</sub>	Asynchronous Removal Time		0.00		0.00		0.00	ns
t <sub>CLR</sub>	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t <sub>PRESET</sub>	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

## LVPECL

Low-Voltage Positive Emitter-Coupled Logic (LVPECL) is another differential I/O standard. It requires that one data bit is carried through two signal lines. Like LVDS, two pins are needed. It also requires external resistor termination. The voltage swing between these two signal lines is approximately 850 mV.



**Figure 2-26 • LVPECL Board-Level Implementation**

The LVPECL circuit is similar to the LVDS scheme. It requires four external resistors, three for the driver and one for the receiver. The values for the three driver resistors are different from that of LVDS since the output voltage levels are different. Please note that the VOH levels are 200 mV below the standard LVPECL levels.

**Table 2-59 • DC Input and Output Levels**

DC Parameter	Min.		Typ.		Max.		Units
	Min.	Max.	Min.	Max.	Min.	Max.	
VCCI		3		3.3		3.6	V
VOH	1.8	2.11	1.92	2.28	2.13	2.41	V
VOL	0.96	1.27	1.06	1.43	1.3	1.57	V
VIH	1.49	2.72	1.49	2.72	1.49	2.72	V
VIL	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential Input Voltage	0.3		0.3		0.3		V

**Table 2-60 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)
1.6 – 0.3	1.6 + 0.3	1.6

Note: \* Measuring Point = VTRIP

## Carry-Chain Logic

The Axcelerator dedicated carry-chain logic offers a very compact solution for implementing arithmetic functions without sacrificing performance.

To implement the carry-chain logic, two C-cells in a Cluster are connected together so the FCO (i.e. carry out) for the two bits is generated in a carry look-ahead scheme to achieve minimum propagation delay from the FCI (i.e. carry in) into the two-bit Cluster. The two-bit carry logic is shown in Figure 2-29.

The FCI of one C-cell pair is driven by the FCO of the C-cell pair immediately above it. Similarly, the FCO of one C-cell pair, drives the FCI input of the C-cell pair immediately below it (Figure 1-4 on page 1-3 and Figure 2-30 on page 2-57).

The carry-chain logic is selected via the CFN input. When carry logic is not required, this signal is deasserted to save power. Again, this configuration is handled automatically for the user through Microsemi's macro library.

The signal propagation delay between two C-cells in the carry-chain sequence is 0.1 ns.

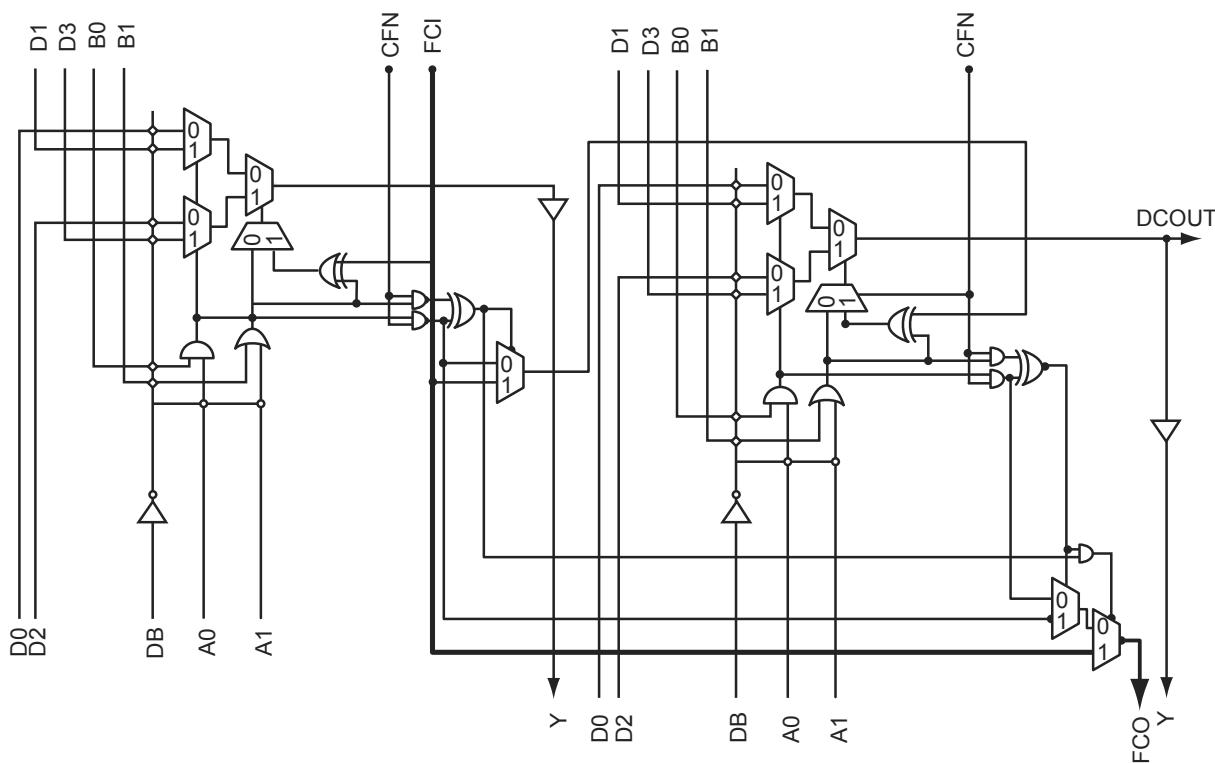


Figure 2-29 • Axcelerator's Two-Bit Carry Logic

## Global Resource Distribution

At the root of each global resource is a PLL. There are two groups of four PLLs for every device. One group, located at the center of the north edge (in the I/O ring) of the chip, sources the four HCLKs. The second group, located at the center of the south edge (again in the I/O ring), sources the four CLKS (Figure 2-38).

Regardless of the type of global resource, HCLK or CLK, each of the eight resources reach the ClockTileDist (CTD) Cluster located at the center of every core tile with zero skew. From the ClockTileDist Cluster, all four HCLKs and four CLKS are distributed through the core tile (Figure 2-39).

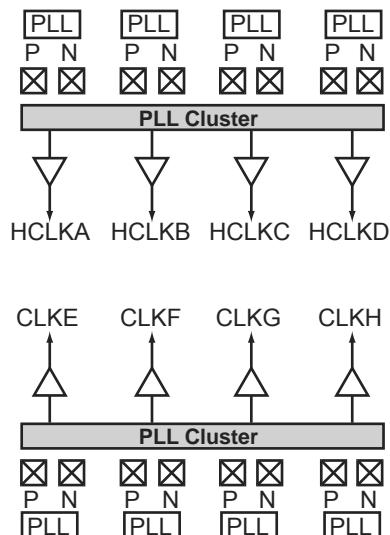


Figure 2-38 • PLL Group

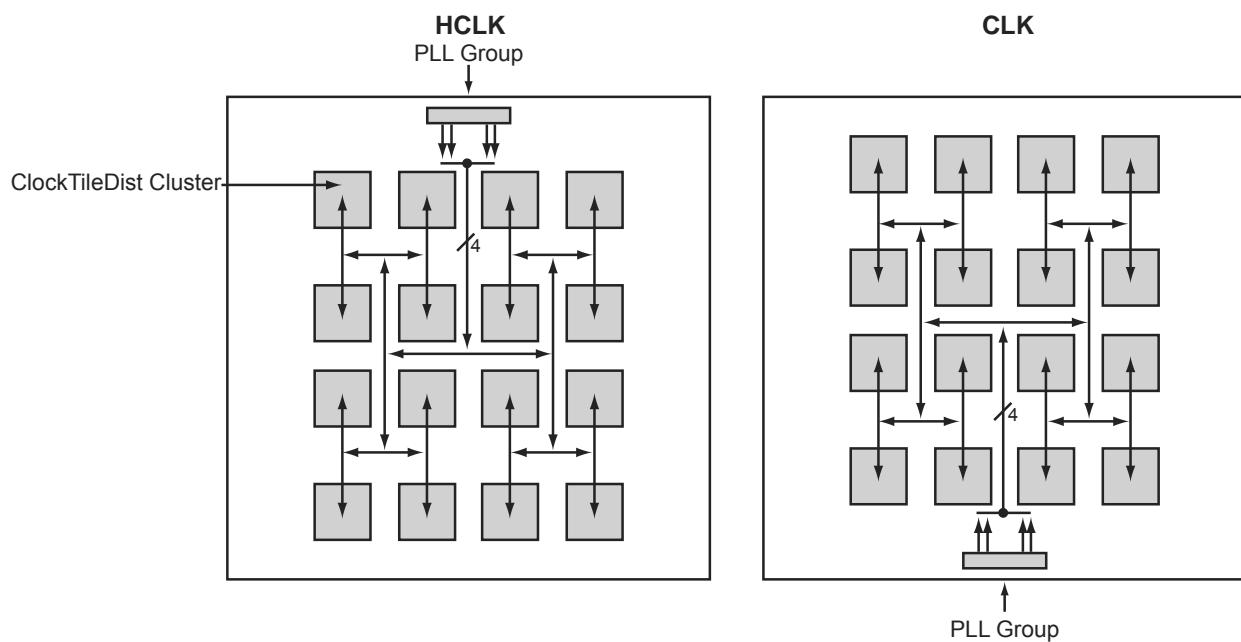


Figure 2-39 • Example of HCLK and CLK Distributions on the AX2000

single-ended, or voltage-referenced standard. The [H]CLKxN pad can only be used as a differential pair with [H]CLKxP.

The block marked “/i Delay Match” is a fixed delay equal to that of the i divider. The “/j Delay Match” block has the same function as its j divider counterpart.

## Functional Description

Figure 2-48 on page 2-75 illustrates a block diagram of the PLL. The PLL contains two dividers, i and j, that allow frequency scaling of the clock signal:

- The i divider in the feedback path allows multiplication of the input clock by integer factors ranging from 1 to 64, and the resultant frequency is available at the output of the PLL block.
- The j divider divides the PLL output by integer factors ranging from 1 to 64, and the divided clock is available at CLK1.
- The two dividers together can implement any combination of multiplication and division up to a maximum frequency of 1 GHz on CLK1. Both the CLK1 and CLK2 outputs have a fixed 50/50 duty cycle.
- The output frequencies of the two clocks are given by the following formulas ( $f_{REF}$  is the reference clock frequency):
 
$$f_{CLK1} = f_{REF} * (\text{DividerI}) / (\text{DividerJ}) \quad \text{EQ 4}$$

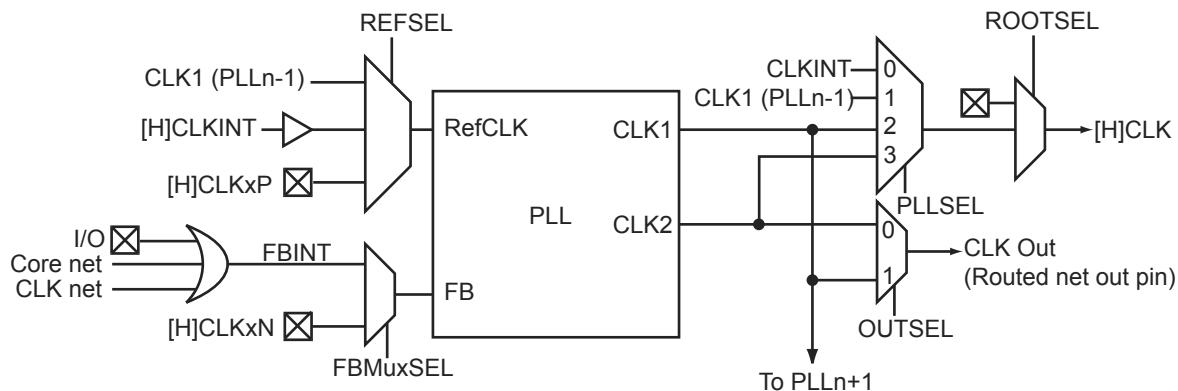
$$f_{CLK2} = f_{REF} * (\text{DividerI}) \quad \text{EQ 5}$$

- CLK2 provides the PLL output directly—without division

The input and output frequency ranges are selected by LowFreq and Osc(2:0), respectively. These functions and their possible values are detailed in Table 2-80 on page 2-77.

The delay lines shown in Figure 2-48 on page 2-75 are programmable. The feedback clock path can be delayed (using the five DelayLine bits) relative to the reference clock (or vice versa) by up to 3.75 ns in increments of 250 ps. Table 2-80 on page 2-77 describes the usage of these bits. The delay increments are independent of frequency, so this results in phase changes that vary with frequency. The delay value is highly dependent on  $V_{CC}$  and the speed grade.

Figure 2-49 is a logical diagram of the various control signals to the PLL and shows how the PLL interfaces with the global and routing networks of the FPGA. Note that not all signals are user-accessible. These non-user-accessible signals are used by the place-and-route tool to control the configuration of the PLL. The user gains access to these control signals either based upon the connections built in the user's design or through the special macros (Table 2-84 on page 2-81) inserted into the design. For example, connecting the macro PLLOUT to CLK2 will control the OUTSEL signal.



*Note: Not all signals are available to the user.*

Figure 2-49 • PLL Logical Interface

## CLK1 and CLK2

Both PLL outputs, CLK1 and CLK2, can be used to drive a global resource, an adjacent PLL RefCLK input, or a net in the FPGA core. Not all drive combinations are possible (Table 2-81).

**Table 2-81 • PLL General Connections Rules**

CLK1	CLK2
HCLK	HCLK
CLK	CLK
HCLK	Routed net output
Routed net output	HCLK
HCLK	NONE
NONE	HCLK
CLK	NONE
NONE	CLK

Note: *The PLL outputs remain Low when REFCLK is constant (either Low or High).*

## Restrictions on CLK1 and CLK2

- When both are driving global resources, they must be driving the same type of global resource (i.e. either HCLK or CLK).
- Only one can drive a routed net at any given time.

Table 2-82 and Table 2-83 specify all the possible CLK1 and CLK2 connections for the north and south PLLs. HCLK1 and HCLK2 are used to denote the different HCLK networks when two are being driven at the same time by a single PLL (Note that HCLK1 is the primary clock resource associated with the PLL, and HCLK2 is the clock resource associated with the adjacent PLL). Likewise, CLK1 and CLK2 are used to denote the different CLK networks when two are being driven at the same time by a single PLL (Figure 2-48 on page 2-75).

**Table 2-82 • North PLL Connections**

CLK1	CLK2
HCLK1	Routed net
HCLK1	Unused
HCLK2	HCLK1
HCLK2	Routed net
HCLK2	Both HCLK1 and routed net
HCLK2	Unused
Unused	HCLK1
Unused	Routed net
Unused	Both HCLK1 and routed net
Unused	Unused
Routed net	HCLK1
Routed net	Unused
Both HCLK1 and HCLK2	Routed net
Both HCLK1 and HCLK2	Unused
Both HCLK1 and routed net	Unusable
Both HCLK2 and routed net	HCLK1
Both HCLK2 and routed net	Unused
HCLK1, HCLK2, and routed net	Unusable

Note: *Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g. CLK1 driving HCLK1, and HCLK2 is not supported).*

**Table 2-99 • Two FIFO Blocks Cascaded**Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T<sub>J</sub> = 70°C

Parameter	Description	–2 Speed		–1 Speed		Std Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>FIFO Module Timing</b>								
t <sub>WSU</sub>	Write Setup		13.75		15.66		18.41	ns
t <sub>WHD</sub>	Write Hold		0.00		0.00		0.00	ns
t <sub>WCKH</sub>	WCLK High		0.75		0.75		0.75	ns
t <sub>WCKL</sub>	WCLK Low		1.76		1.76		1.76	ns
t <sub>WCKP</sub>	Minimum WCLK Period	2.51		2.51		2.51		ns
t <sub>RSU</sub>	Read Setup		14.33		16.32		19.19	ns
t <sub>RHD</sub>	Read Hold		0.00		0.00		0.00	ns
t <sub>RCKH</sub>	RCLK High		0.73		0.73		0.73	ns
t <sub>RCKL</sub>	RCLK Low		1.89		1.89		1.89	ns
t <sub>RCKP</sub>	Minimum RCLK period	2.62		2.62		2.62		ns
t <sub>CLRHF</sub>	Clear High		0.00		0.00		0.00	ns
t <sub>CLR2FF</sub>	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t <sub>CLR2AF</sub>	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t <sub>CK2FF</sub>	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t <sub>CK2AF</sub>	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
t <sub>RCK2RD1</sub>	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
t <sub>RCK2RD2</sub>	RCLK-To-OUT (Nonpipelined)		2.26		2.58		3.03	ns

Note: Timing data for these two cascaded FIFO blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.



<b>BG729</b>	
<b>AX1000 Function</b>	<b>Pin Number</b>
GND	B27
GND	B3
GND	C1
GND	C2
GND	C25
GND	C26
GND	C27
GND	C3
GND	E27
GND	L11
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17

<b>BG729</b>	
<b>AX1000 Function</b>	<b>Pin Number</b>
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND/LP	J8
NC	U3
PRA	J14
PRB	D14
PRC	V14
PRD	AB14
TCK	E4
TDI	D4
TDO	J9
TMS	H8
TRST	E3
VCCA	AA21
VCCA	AD5
VCCA	E1
VCCA	G22
VCCA	K10

<b>BG729</b>	
<b>AX1000 Function</b>	<b>Pin Number</b>
VCCA	K11
VCCA	K17
VCCA	K18
VCCA	L10
VCCA	L18
VCCA	U10
VCCA	U18
VCCA	V10
VCCA	V11
VCCA	V17
VCCA	V18
VCCPLA	A13
VCCPLB	J13
VCCPLC	B15
VCCPLD	C15
VCCPLE	AG14
VCCPLF	AF14
VCCPLG	AB13
VCCPLH	AG13
VCCDA	A11
VCCDA	AB12
VCCDA	AC12
VCCDA	AC25
VCCDA	AD16
VCCDA	AD17
VCCDA	E16
VCCDA	E2
VCCDA	E24
VCCDA	F12
VCCDA	F16
VCCDA	F7
VCCDA	K14
VCCDA	P10
VCCDA	P18
VCCDA	W14
VCCDA	W9
VCCIB0	A4

FG676	
AX500 Function	Pin Number
<b>Bank 0</b>	
IO00NB0F0	F8
IO00PB0F0	E8
IO01NB0F0	A5
IO01PB0F0	A4
IO02NB0F0	E7
IO02PB0F0	E6
IO03NB0F0	D6
IO03PB0F0	D5
IO04NB0F0	B5
IO04PB0F0	C5
IO05NB0F0	B6
IO05PB0F0	C6
IO06NB0F0	C7
IO06PB0F0	D7
IO07NB0F0	A7
IO07PB0F0	A6
IO08NB0F0	C8
IO08PB0F0	D8
IO09NB0F0	F10
IO09PB0F0	F9
IO10NB0F0	B8
IO10PB0F0	B7
IO11NB0F0	D10
IO11PB0F0	E10
IO12NB0F1	B9
IO12PB0F1	C9
IO13NB0F1	F11
IO13PB0F1	G11
IO14NB0F1	D11
IO14PB0F1	E11
IO15NB0F1	B10
IO15PB0F1	C10
IO16NB0F1	A10
IO16PB0F1	A9

FG676	
AX500 Function	Pin Number
<b>Bank 1</b>	
IO17NB0F1	F12
IO17PB0F1	G12
IO18NB0F1	C12
IO18PB0F1	C11
IO19NB0F1/HCLKAN	A12
IO19PB0F1/HCLKAP	B12
IO20NB0F1/HCLKBN	C13
IO20PB0F1/HCLKBP	B13
<b>Bank 2</b>	
IO21NB1F2/HCLKCN	C15
IO21PB1F2/HCLKCP	C14
IO22NB1F2/HCLKDN	A15
IO22PB1F2/HCLKDP	B15
IO23NB1F2	F15
IO23PB1F2	G15
IO24NB1F2	B16
IO24PB1F2	A16
IO25NB1F2	A18
IO25PB1F2	A17
IO26NB1F2	D16
IO26PB1F2	E16
IO27NB1F2	F16
IO27PB1F2	G16
IO28NB1F2	C18
IO28PB1F2	C17
IO29NB1F2	B19
IO29PB1F2	B18
IO30NB1F2	D19
IO30PB1F2	C19
IO31NB1F2	F17
IO31PB1F2	E17
IO32NB1F3	B20
IO32PB1F3	A20
IO33NB1F3	B22
IO33PB1F3	B21

FG676	
AX500 Function	Pin Number
IO34NB1F3	D20
IO34PB1F3	C20
IO35NB1F3	D21
IO35PB1F3	C21
IO36NB1F3	D22
IO36PB1F3	C22
IO37NB1F3	F19
IO37PB1F3	E19
IO38NB1F3	B23
IO38PB1F3	A23
IO39NB1F3	E21
IO39PB1F3	E20
IO40NB1F3	D23
IO40PB1F3	C23
IO41NB1F3	D25
IO41PB1F3	C25
<b>Bank 2</b>	
IO42NB2F4	G24
IO42PB2F4	G23
IO43NB2F4	G26
IO43PB2F4	F26
IO44NB2F4	F25
IO44PB2F4	E25
IO45NB2F4	J21
IO45PB2F4	J22
IO46NB2F4	H25
IO46PB2F4	G25
IO47NB2F4	K23
IO47PB2F4	J23
IO48NB2F4	J24
IO48PB2F4	H24
IO49NB2F4	K21
IO49PB2F4	K22
IO50NB2F4	K25
IO50PB2F4	J25

<b>FG896</b>	
<b>AX2000 Function</b>	<b>Pin Number</b>
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10

<b>FG896</b>	
<b>AX2000 Function</b>	<b>Pin Number</b>
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

FG1152		FG1152		FG1152	
AX2000 Function	Pin Number	AX2000 Function	Pin Number	AX2000 Function	Pin Number
IO311NB7F29	N3	IO328PB7F30	N9	GND	A33
IO311PB7F29	P3	IO329NB7F30	J4	GND	A4
IO312NB7F29	P7	IO329PB7F30	K4	GND	A8
IO312PB7F29	R7	IO330NB7F30	J5	GND	AA14
IO313NB7F29	P6	IO330PB7F30	K5	GND	AA15
IO313PB7F29	R6	IO331NB7F30	M10	GND	AA16
IO314NB7F29	M2	IO331PB7F30	M9	GND	AA17
IO314PB7F29	N2	IO332NB7F31	L8	GND	AA18
IO315NB7F29	N4	IO332PB7F31	M8	GND	AA19
IO315PB7F29	P4	IO333NB7F31	F2	GND	AA20
IO316NB7F29	R9	IO333PB7F31	F1	GND	AA21
IO316PB7F29	R8	IO334NB7F31	J6	GND	AB1
IO317NB7F29	N5	IO334PB7F31	K6	GND	AB13
IO317PB7F29	P5	IO335NB7F31	H4	GND	AB22
IO318NB7F29	R10	IO335PB7F31	H3	GND	AB34
IO318PB7F29	R11	IO336NB7F31	K7	GND	AC12
IO319NB7F29	L2	IO336PB7F31	L7	GND	AC23
IO319PB7F29	L1	IO337NB7F31	G4	GND	AC30
IO320NB7F29	N8	IO337PB7F31	G3	GND	AC5
IO320PB7F29	P8	IO338NB7F31	K9	GND	AD11
IO321NB7F30	M6	IO338PB7F31	L9	GND	AD24
IO321PB7F30	N6	IO339NB7F31	H6	GND	AD31
IO322NB7F30	P10	IO339PB7F31	H5	GND	AD4
IO322PB7F30	P9	IO340NB7F31	H7	GND	AE3
IO323NB7F30	L3	IO340PB7F31	J7	GND	AE32
IO323PB7F30	M3	IO341NB7F31	J8	GND	AF2
IO324NB7F30	M7	IO341PB7F31	K8	GND	AF33
IO324PB7F30	N7	Dedicated I/O		GND	AG1
IO325NB7F30	K2	GND	A13	GND	AG27
IO325PB7F30	K1	GND	A2	GND	AG34
IO326NB7F30	G2	GND	A22	GND	AG8
IO326PB7F30	H2	GND	A27	GND	AH28
IO327NB7F30	L6	GND	A3	GND	AH7
IO327PB7F30	L5	GND	A31	GND	AJ29
IO328NB7F30	N10	GND	A32	GND	AJ6

FG1152	
AX2000 Function	Pin Number
NC	AP9
NC	B17
NC	B22
NC	B27
NC	B8
NC	D10
NC	D20
NC	D23
NC	D25
NC	F3
NC	F32
NC	F33
NC	F34
NC	F4
NC	G1
NC	G32
NC	G33
NC	G34
NC	H31
NC	H33
NC	J1
NC	J3
NC	J34
NC	M1
NC	M4
NC	P1
NC	P2
NC	R31
NC	T1
NC	T2
NC	V3
NC	V34
NC	W3
NC	W34
PRA	J17

FG1152	
AX2000 Function	Pin Number
PRB	F18
PRC	AD18
PRD	AH18
TCK	J9
TDI	F7
TDO	L10
TMS	H8
TRST	E6
VCCA	AA13
VCCA	AA22
VCCA	AB14
VCCA	AB15
VCCA	AB16
VCCA	AB17
VCCA	AB18
VCCA	AB19
VCCA	AB20
VCCA	AB21
VCCA	AF8
VCCA	AK28
VCCA	G30
VCCA	G5
VCCA	N14
VCCA	N15
VCCA	N16
VCCA	N17
VCCA	N18
VCCA	N19
VCCA	N20
VCCA	N21
VCCA	P13
VCCA	P22
VCCA	R13
VCCA	R22
VCCA	T13

FG1152	
AX2000 Function	Pin Number
VCCA	T22
VCCA	U13
VCCA	U22
VCCA	V13
VCCA	V22
VCCA	W13
VCCA	W22
VCCA	Y13
VCCA	Y22
VCCDA	AF26
VCCDA	AF9
VCCDA	AG17
VCCDA	AG18
VCCDA	AH14
VCCDA	AH15
VCCDA	AH17
VCCDA	AH20
VCCDA	AH21
VCCDA	AK29
VCCDA	AK6
VCCDA	E15
VCCDA	E29
VCCDA	E7
VCCDA	F15
VCCDA	F21
VCCDA	F5
VCCDA	G20
VCCDA	H17
VCCDA	H18
VCCDA	H28
VCCDA	J18
VCCDA	V27
VCCDA	V6
VCCIB0	A5
VCCIB0	B5

FG1152	
AX2000 Function	Pin Number
VCOMPLD	K18
VCOMPLE	AH19
VCOMPLF	AF18
VCOMPLG	AH16
VCOMPLH	AD17
VPUMP	J26

CG624		CG624		CG624	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO131NB4F12	V19	IO153NB4F14	Y15	IO173PB5F16	Y11
IO131PB4F12	W19	IO153PB4F14	Y16	IO174NB5F16	AB10
IO133NB4F12	Y18	IO155NB4F14	V15	IO174PB5F16	AB11
IO133PB4F12	Y19	IO155PB4F14	V16	IO175NB5F16	AC9
IO135NB4F12	W18	IO156NB4F14	AB14	IO175PB5F16	AE9
IO135PB4F12	V18	IO156PB4F14	AB15	IO177NB5F16	AA8
IO137NB4F12	Y17	IO157NB4F14	AE14	IO177PB5F16	Y8
IO137PB4F12	AA17	IO157PB4F14	AC18	IO178NB5F16	Y6
IO138NB4F12	AB19	IO158NB4F14	AC15	IO178PB5F16	W6
IO138PB4F12	AB18	IO158PB4F14	AC19	IO179PB5F16	W10
IO139NB4F13	AA19	IO159NB4F14/CLKEN	W14	IO180NB5F16	Y7
IO139PB4F13	U18	IO159PB4F14/CLKEP	W15	IO180PB5F16	W7
IO140NB4F13	AC20	IO160NB4F14/CLKFN	AC13	IO181NB5F17	AD9
IO140PB4F13	AC21	IO160PB4F14/CLKFP	AD13	IO181PB5F17	AD10
IO141NB4F13	AD17	<b>Bank 5</b>		IO182NB5F17	AE10
IO141PB4F13	AD18	IO161NB5F15/CLKGN	W13	IO182PB5F17	AE11
IO142NB4F13	AD21	IO161PB5F15/CLKGP	Y13	IO183NB5F17	AD7
IO142PB4F13	AD22	IO162NB5F15/CLKHN	AC12	IO183PB5F17	AD8
IO143NB4F13	AB17	IO162PB5F15/CLKHP	AD12	IO184NB5F17	AB9
IO143PB4F13	AC17	IO163NB5F15	V9	IO185NB5F17	AE6
IO144PB4F13	AE22	IO163PB5F15	V10	IO185PB5F17	AE7
IO145NB4F13	AE15	IO164NB5F15	V11	IO186NB5F17	AE4
IO145PB4F13	AE16	IO164PB5F15	T13	IO186PB5F17	AE5
IO146NB4F13	AD19	IO165NB5F15	U13	IO187NB5F17	AA9
IO146PB4F13	AD20	IO165PB5F15	V13	IO187PB5F17	Y9
IO147NB4F13	AD15	IO167NB5F15	W11	IO188NB5F17	U8
IO147PB4F13	AD16	IO167PB5F15	W12	IO189NB5F17	AD5
IO148PB4F13	AE21	IO168NB5F15	AB6	IO189PB5F17	AD6
IO149NB4F13	AD14	IO168PB5F15	AA6	IO191NB5F17	AC5
IO149PB4F13	AC14	IO169NB5F15	V8	IO191PB5F17	AC6
IO150NB4F13	AE19	IO169PB5F15	V7	IO192NB5F17	AB7
IO150PB4F13	AE20	IO171NB5F16	W8	IO192PB5F17	AC7
IO151NB4F13	V17	IO171PB5F16	W9	<b>Bank 6</b>	
IO151PB4F13	W17	IO172NB5F16	AB8	IO193NB6F18	U6
IO152NB4F14	AB16	IO172PB5F16	AC8	IO193PB6F18	U5
IO152PB4F14	W16	IO173NB5F16	AA11		